

SBOS185D – JANUARY 2001 – REVISED MARCH 2003

Dual, VARIABLE GAIN AMPLIFIER with Input Buffer

FEATURES

- GAIN RANGE: 40dB40MHz BANDWIDTH
- LOW CROSSTALK: 70dB at Max Gain, 5MHz
- HIGH-SPEED VARIABLE GAIN ADJUST
- POWER SHUTDOWN MODE
- HIGH IMPEDANCE INPUT BUFFER

APPLICATIONS

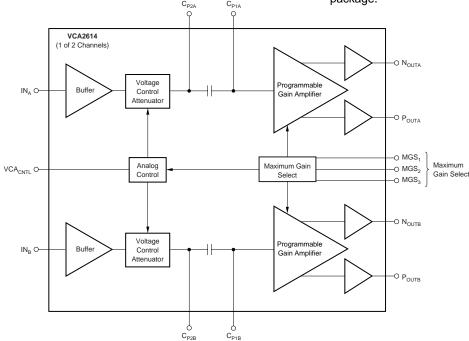
- ULTRASOUND SYSTEMS
- GAMMA CAMERAS
- WIRELESS RECEIVERS
- TEST EQUIPMENT

DESCRIPTION

The VCA2614 is a highly integrated, dual receive channel, Variable Gain Amplifier (VGA) with analog gain control.

The VCA2614's VGA section consists of two parts: the Voltage Controlled Attenuator (VCA) and the Programmable Gain Amplifier (PGA). The gain and gain range of the PGA can be digitally programmed. The combination of these two programmable elements results in a variable gain ranging from 0dB up to a maximum gain as defined by the user through external connections. The single-ended unity gain input buffer provides predictable high input impedance. The output of the VGA can be used in either a single-ended or differential mode to drive high-performance Analog-to-Digital Converters (ADCs). A separate power-down pin reduces power consumption.

The VCA2614 also features low crosstalk and outstanding distortion performance. The combination of low noise and gain range programmability makes the VCA2614 a versatile building block in a number of applications where noise performance is critical. The VCA2614 is available in a TQFP-32 package.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ABSOLUTE MAXIMUM RATINGS(1)

Power Supply (+V _S)	+6V
Analog Input	
Logic Input	0.3V to (+V _S + 0.3V)
Case Temperature	+100°C
Junction Temperature	+150°C
Storage Temperature	40°C to +150°C

NOTE: (1) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods may affect device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
VCA2614Y	TQFP-32 Surface-Mount	PBS "	–40°C to +85°C "	VCA2614Y "	VCA2614Y/250 VCA2614Y/2K	Tape and Reel, 250 Tape and Reel, 2000

NOTE: (1) For the most current specifications and package information, refer to our web site at www.ti.com.

ELECTRICAL CHARACTERISTICS

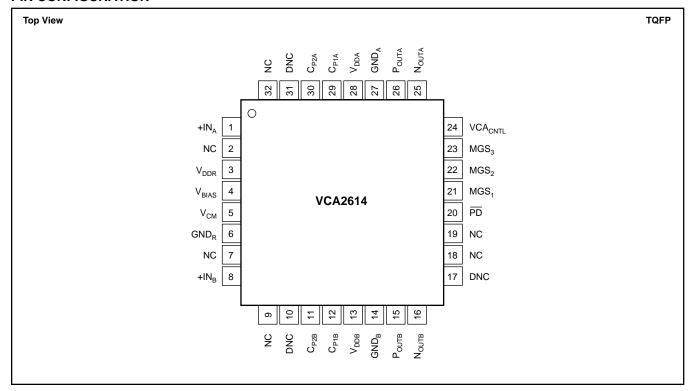
At T_A = +25°C, V_{DD} = 5V, load resistance = 500Ω on each output to ground differential output (2Vp-p), MGS = 011, and f_{IN} = 5MHz, unless otherwise noted.

			VCA2614Y		
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
BUFFER					
Input Resistance			600		kΩ
Input Capacitance			5		pF
Input Bias Current			1		nA
Maximum Input Voltage			1		Vp- <u>p</u>
Input Voltage Noise	MGS = 111, PGA Gain = 44.2dB, $R_S = 50\Omega$		4.8		nV/√Hz
Input Current Noise	Independent of Gain		350		fA/√Hz
Noise Figure	$R_F = 550\Omega$, PGA Gain = 44.2dB, $R_S = 75\Omega$		13		dB
Bandwidth			100		MHz
PROGRAMMABLE VARIABLE GAIN A	MPLIFIER				
Peak Input Voltage			1		Vp-p
-3dB Bandwidth			40		MHz
Slew Rate			300		V/μs
Output Signal Range	$R_L \ge 500\Omega$ Each Side to Ground		2.5 ±1		V
Output Impedance	f = 5MHz		1		Ω
Output Short-Circuit Current			±40		mA
3rd-Harmonic Distortion	$f = 5MHz$, $V_{OUT} = 2Vp-p$, $VCA_{CNTL} = 3.0V$	-45	-60		dBc
2nd-Harmonic Distortion	$f = 5MHz$, $V_{OUT} = 2Vp-p$, $VCA_{CNTL} = 3.0V$	-45	-50		dBc
Overload Performance (2nd-Harmonic	Input Signal = 1Vp-p, MGS = 111, VCA _{CNTL} = 2V		-40 to -45		dB
Distortion)					
Time Delay			5		ns
IMD, 2-Tone	$V_{OUT} = 2Vp-p, f = 9.95MHz$		-59		dBc
Crosstalk			70		dB
Group Delay Variation	1MHz < f < 10MHz, Full Gain Range		13		ns
ACCURACY					
Gain Slope			10.5		dB/V
Gain Error				±2 ⁽¹⁾	dB
Output Offset Voltage			±50		mV
GAIN CONTROL INTERFACE					
Input Voltage (VCA _{CNTL}) Range			0.2 to 3.0		V
Input Resistance			1		$M\Omega$
Response Time	40dB Gain Change, MGS = 111		0.2		μs
POWER SUPPLY	-				-
Specified Operating Range		4.75	5.0	5.25	V
Power Dissipation	Operating, Each Channel		120	150	mW
Power-Down	·		9.2		mW

NOTE: (1) Referenced to best fit dB-linear curve.



PIN CONFIGURATION



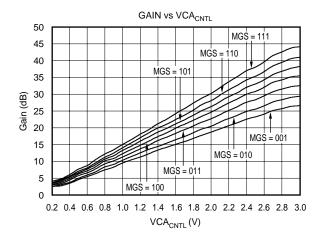
PIN DESCRIPTIONS

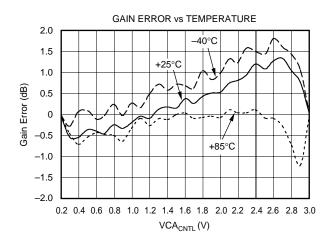
PIN	DESIGNATOR	DESCRIPTION	PIN	DESIGNATOR	DESCRIPTION
1	+IN _A	Input Channel A	17	DNC	Do Not Connect
2	NC	No Internal Connection	18	NC	No Internal Connection
3	V_{DDR}	Internal Reference Supply	19	NC	No Internal Connection
4	V _{BIAS}	Bias Voltage	20	PD	Power Down (Active LOW)
5	V _{CM}	Common-Mode Voltage	21	MGS₁	Maximum Gain Select 1 (MSB)
6	GND _R	Internal Reference Ground	22	MGS ₂	Maximum Gain Select 2
7	NC	No Internal Connection	23	MGS ₃	Maximum Gain Select 3 (LSB)
8	+IN _B	Input Channel B	24	VCA _{CNTL}	VCA Analog Control
9	NC	No Internal Connection	25	N _{OUTA}	Negative VCA Output Channel A
10	DNC	Do Not Connect	26	P _{OUTA}	Positive VCA Output Channel A
11	C _{P2B}	Coupling Capacitor Channel B	27	GND _A	Ground Channel A
12	C _{P1B}	Coupling Capacitor Channel B	28	V_{DDA}	+5V Supply Channel A
13	V_{DDB}	+5V Supply Channel B	29	C _{P1A}	Coupling Capacitor Channel A
14	GND _B	Ground Channel B	30	C _{P2A}	Coupling Capacitor Channel A
15	P _{OUTB}	Positive Output Channel B	31	DNC	Do Not Connect
16	N _{OUTB}	Negative Output Channel B	32	NC	No Internal Connection

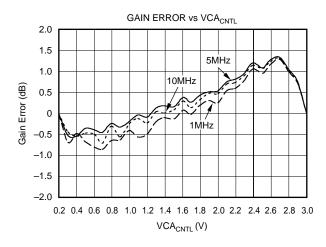


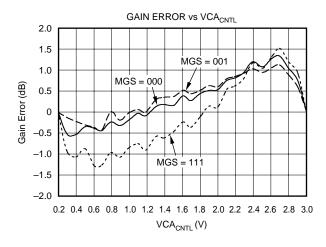


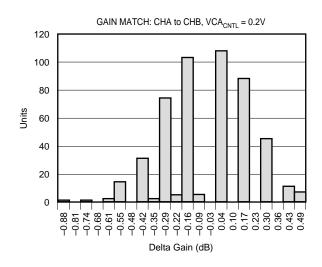
TYPICAL CHARACTERISTICS

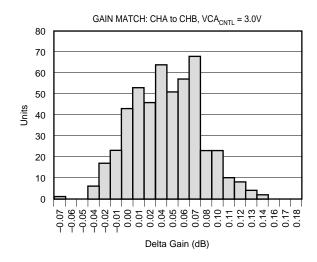




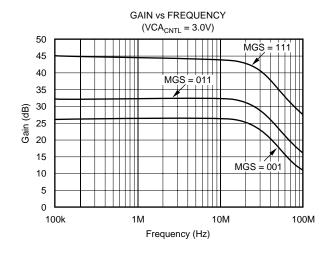


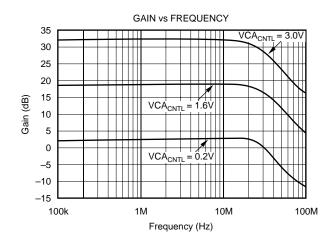


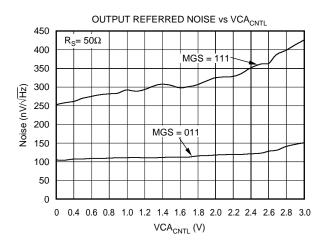


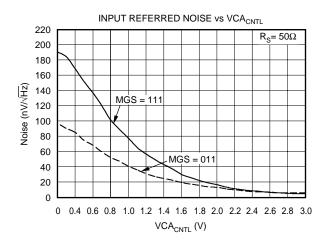


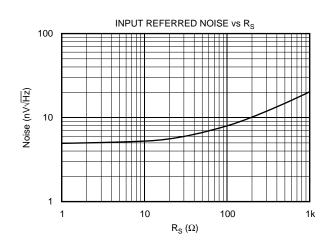


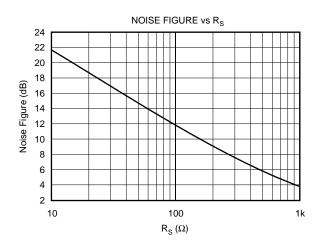






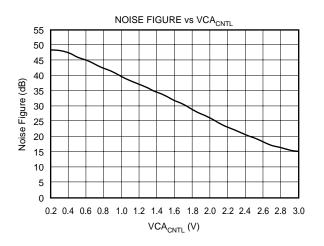


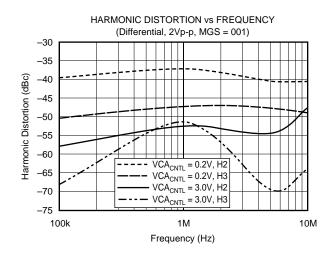


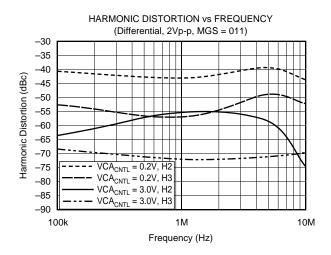


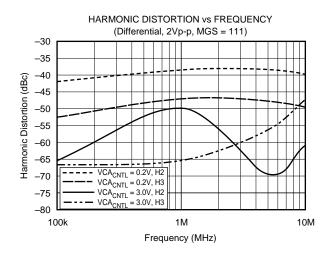


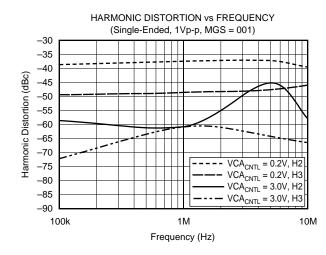


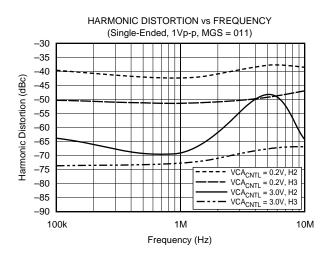




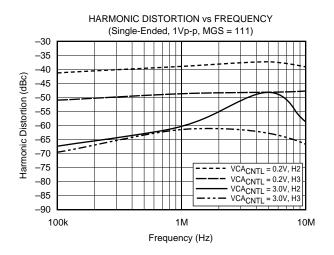


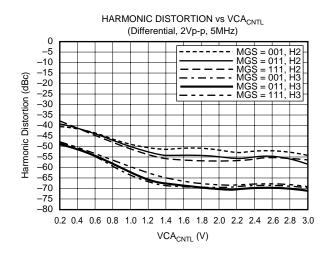


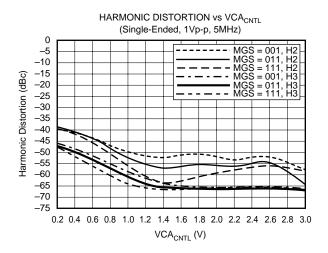


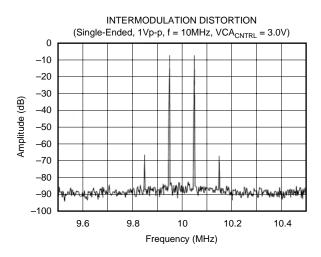


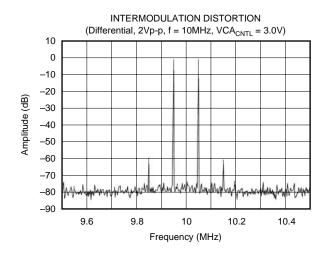


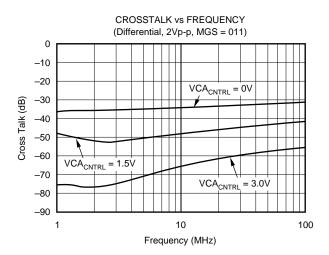






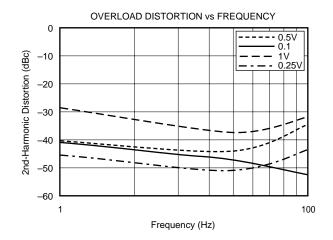


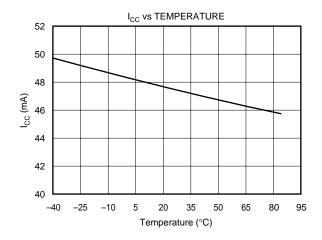


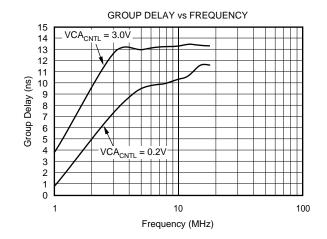












OVERVIEW

The VCA2614 is a dual-channel, VGA consisting of three primary blocks: an Input Buffer, a VCA, and a PGA (as shown in Figure 1). All stages are AC-coupled with the coupling into the PGA stage being made variable by placing an external capacitor between the C_{P1} and C_{P2} pins. This will be discussed further in the PGA section. By using the internal coupling into the PGA, the result is a high-pass filter characteristic with cutoff at approximately 75kHz. The output PGA naturally rolls off at around 40MHz, making the usable bandwidth of the VCA2614 between 75kHz and 40MHz.

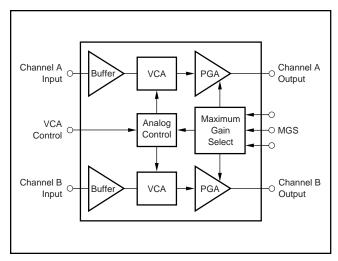


FIGURE 1. Simplified Block Diagram of the VCA2614.

INPUT BUFFER

The input buffer is a unity gain amplifier (gain of +1) with a bandwidth of 100MHz with an input resistance of approximately $600k\Omega$. The input buffer isolates the circuit driving the VCA2614 inputs from the internal VCA block, which would present a varying impedance to the input circuitry. To allow symmetrical operation of the input buffer, the input to the buffer must be AC-coupled through an external capacitor. The recommended value of the capacitor is $0.01\mu F$. It should be noted that if the capacitor value were increased, the

power-on time of the VCA2614 would be increased. If a decrease in the power-on time is needed, the value can be decreased to no less than 100pF.

VOLTAGE-CONTROLLED ATTENUATOR

The magnitude of the VCA input signal from the input buffer is reduced by a programmable attenuation factor, set by the analog VCA Control Voltage (VCA $_{\rm CNTL}$) at pin 24. The maximum attenuation is programmable by using the three MGS bits (pins 21, 22, and 23). Figure 2 illustrates this dual-adjust characteristic.

The MGS bits adjust the overall range of attenuation and maximum gain while the VCA_{CNTL} voltage adjusts the actual attenuation factor. At any given maximum gain setting, the analog variable gain characteristic is linear in dB as a function of the control voltage, and is created as a piecewise approximation of an ideal dB-linear transfer function, see Figure 4. The VCA control circuitry is common to both channels of the VCA2614. The range for the VCA_{CNTL} input spans from 0V to 3V. Although overdriving the VCA_{CNTL} input above the recommended 3V maximum will not damage the part, this condition should be avoided.

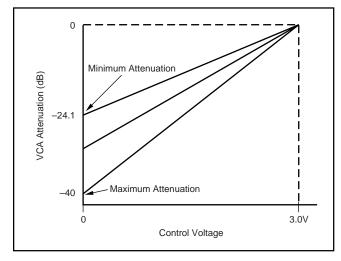


FIGURE 2. Swept Attenuator Characteristic.

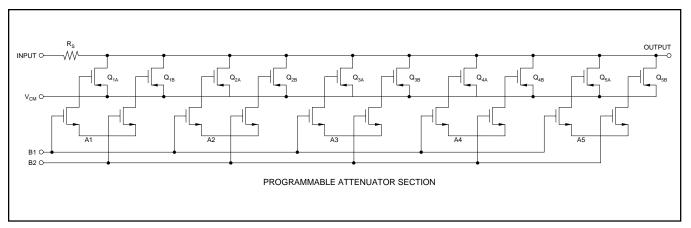


FIGURE 3. Programmable Attenuator Section.





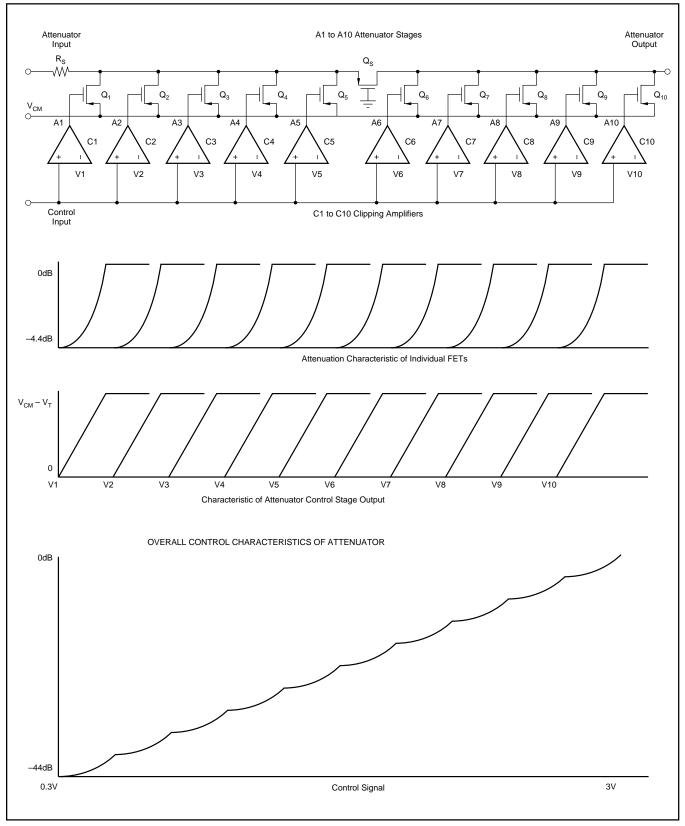


FIGURE 4. Piecewise Approximation to Logarithmic Control Characteristics.

PGA POST-AMPLIFIER

Figure 5 shows a simplified circuit diagram of the PGA block. As stated before, the input to the PGA is AC-coupled by an internal capacitor. Provisions are made so that an external capacitor can be placed in parallel with the internal capacitor, thus lowering the usable low-frequency bandwidth. The low-frequency bandwidth is set by the following equation:

$$\frac{1}{\left(2 \bullet \pi \bullet 500 \text{k}\Omega \bullet \left(220 \text{pF} + \text{C}_{\text{EXTERNAL}}\right)\right)}$$

where C_{EXTERNAL} is the external capacitor value in picofarads. Care should be taken to avoid using too large a value of capacitor, as this can increase the power-on delay time.

As described previously, the PGA gain is programmed with the same MGS bits that control the VCA maximum attenuation factor. Specifically, the maximum PGA gain at each MGS setting is the inverse (reciprocal) of the maximum VCA attenuation at that setting. Therefore, the VCA + PGA overall gain will always be 0dB (unity) when the analog VCA_{CNTL} input is set to 0V (the maximum attenuation for VCA). For VCA_{CNTL} = 3V (no attenuation), the VCA + PGA gain will be controlled by the programmed PGA gain. For clarity, the gain and attenuation factors are detailed in Table I.

The PGA architecture converts the single-ended signal from the VCA into a differential signal. Low input noise was also a requirement of the PGA design due to the large amount of signal attenuation that can be asserted before the PGA. At minimum VCA attenuation (used for small input signals), the

MGS SETTING	ATTENUATOR GAIN VCA _{CNTL} = 0.02V to 3V	ATTENUATOR + DIFFERENTIAL PGA GAIN
000	Not Valid	Not Valid
001	-24.1dB to 0dB	2.6dB to 26.7dB
010	-26.9dB to 0dB	2.6dB to 29.5dB
011	-29.5dB to 0dB	3.0dB to 35.6dB
100	-32.4dB to 0dB	3.1dB to 35.5dB
101	-34.8dB to 0dB	3.4dB to 38.3dB
110	-37.3dB to 0dB	3.7dB to 44.1dB
111	-40.0dB to 0dB	4.1dB to 44.2dB

TABLE I. MGS Settings.

input buffer noise dominates; at maximum VCA attenuation (large input signals), the PGA noise dominates. Note that if the PGA output is used single-ended, the apparent gain will be 6dB lower.

LAYOUT CONSIDERATIONS

The VCA2614 is an analog amplifier capable of high gain. When working on a PCB layout for the VCA2614, it is recommended to utilize a solid ground plane that is connected to analog ground. This helps to maximize the noise performance of the VCA2614.

Adequate power-supply decoupling must be used in order to achieve the best possible performance. Decoupling capacitors on the VCA_{CNTL} voltage should also be used to help minimize noise. Recommended values can be obtained from the layout diagram of Figure 6.

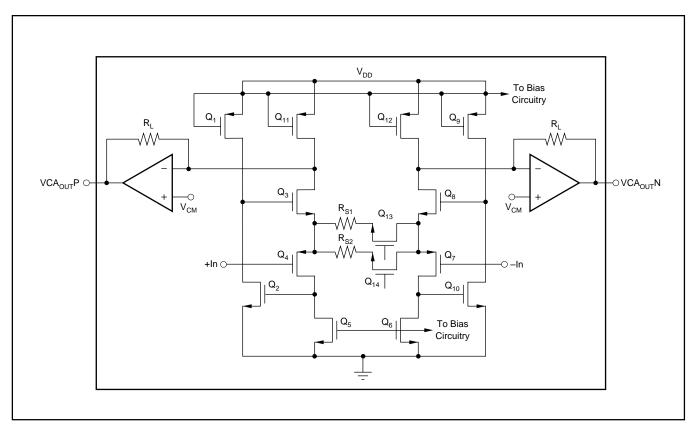


FIGURE 5. Simplified Block Diagram of the PGA Section with the VCA2614.





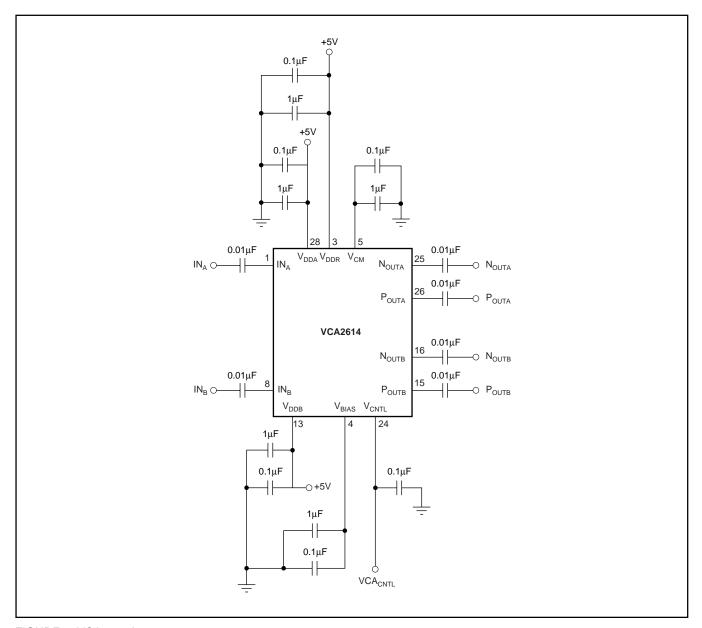


FIGURE 6. VCA2614 Layout.

PACKAGE OPTION ADDENDUM

www.ti.com 15-Apr-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
VCA2614Y/250	ACTIVE	TQFP	PBS	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
VCA2614Y/2K	ACTIVE	TQFP	PBS	32	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

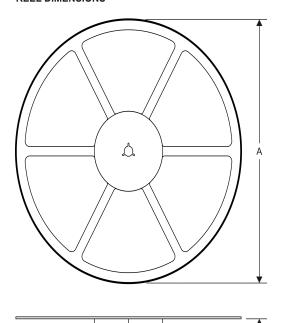
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
VCA2614Y/250	TQFP	PBS	32	250	177.8	16.4	7.2	7.2	1.5	12.0	16.0	Q2
VCA2614Y/2K	TQFP	PBS	32	2000	330.0	16.8	7.2	7.2	1.5	12.0	16.0	Q2

www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
VCA2614Y/250	TQFP	PBS	32	250	210.0	185.0	35.0
VCA2614Y/2K	TQFP	PBS	32	2000	367.0	367.0	38.0

PBS (S-PQFP-G32)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.



PBS (S-PQFP-G32)

PLASTIC QUAD FLATPACK



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- E. Customers should contact their board fabrication site for recommended solder mask tolerances between and around signal pads.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46C and to discontinue any product or service per JESD48B. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

roducts		Applications
udia	ununu ti com/ou dio	Automotive on

Audio Automotive and Transportation www.ti.com/automotive www.ti.com/audio www.ti.com/communications **Amplifiers** amplifier.ti.com Communications and Telecom **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** Consumer Electronics www.ti.com/consumer-apps www.dlp.com DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic logic.ti.com Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

OMAP Mobile Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity

www.ti-rfid.com

Pr